

Specifications	
Part Number	XC5VLX50T-2FF665I
Manufacturer	Xilinx
Description	IC FPGA 360 I/O 665FCBGA
Category	Integrated Circuits (ICs) > Embedded - FPGAs (Field
Part Status	2635 pcs Stock
Voltage - Supply	0.95 V ~ 1.05 V
Total RAM Bits	2211840
Supplier Device Package	665-FCBGA (27x27)
Series	Virtex®-5 LXT
Package / Case	665-BBGA, FCBGA
Operating Temperature	-40°C ~ 100°C (TJ)
Number of Logic Elements/Cells	46080
Number of LABs/CLBs	3600
Number of I/O	360
Mounting Type	Surface Mount

In:



XC5VLX50T-2FFG1136C
Xilinx Inc.
IC FPGA 480 I/O 1136FCBGA



The image shows two components: a square integrated circuit (IC) chip and its corresponding Quad Flat Pack (QFP) package. The chip is a small, square, light-colored silicon die with the text "XILINX VIRTEX-5" printed on it. The package is a larger, square, light-colored component with a grid of pins on all four sides, characteristic of a QFP. The package is labeled with "XC5VLX50T-2FF1136I" and "Xilinx Inc.".



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More

Contact us: **Info@YIC-Electronics.com**
ADD: Unit A5-B5 No.509, 5/F Sing Win Factory Building, 15-17 Shing yip St, Kwun Tong, Kowloon, HongKong.
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